

In the Claims

This listing of claims will replace all prior versions, and listings, of claims.

Listing of Claims

1-8. (Cancelled).

9. (Currently Amended) An interconnect structure, comprising:

a substrate having a surface;

a dielectric layer disposed on the surface of the substrate;

a first metal layer disposed in the dielectric layer, having a first and second end, wherein the direction extending from the first end to the second end is parallel to the substrate surface;

a second metal layer disposed on the dielectric layer, wherein the second metal layer is isolated from the first metal layer by the dielectric layer; and

a plurality of conductive plugs parallel to extending direction of the first metal layer disposed in the dielectric layer and on the first end of the first metal layer to electrically connect the second metal layer,

wherein the first metal layer and the second metal layer are a gate metal layer and a source/drain metal layer of a TFT array respectively.

10. (Original) The interconnect structure as claimed in claim 9, wherein the substrate is a TFT-array substrate for an LCD panel.

11. (canceled) The interconnect structure as claimed in claim 10, wherein the first metal layer and the second metal layer are a gate metal layer and a source/drain metal layer of a TFT array respectively.

12. (Original) The interconnect structure as claimed in claim 9, wherein the number of conductive plugs is from 2 to 5.

13. (Original) The interconnect structure as claimed in claim 9, wherein the conductive plugs disposed on the first end of the first metal layer electrically connect one end of the second metal layer.
14. (Currently Amended) An interconnect structure, comprising:
a substrate having a surface;
a dielectric layer disposed on the surface of the substrate;
a first metal layer disposed in the dielectric layer, having a first and second end, wherein the direction extending from the first end to the second end is parallel to the substrate surface;;
a second metal layer disposed on the dielectric layer; and
a plurality of plugs parallel to extending direction of the first metal layer disposed on the first end of the first metal layer, wherein the plug farther from the first end of the first metal layer is conductive and electrically connects the second metal layer.
15. (Previously Presented) The interconnect structure as claimed in claim 14, wherein the substrate is a TFT-array substrate for an LCD panel.
16. (Previously Presented) The interconnect structure as claimed in claim 14, wherein the number of plugs is from 2 to 5.
17. (Previously Presented) The interconnect structure as claimed in claim 14, wherein the conductive plug electrically connects one end of the second metal layer.
18. (New) An interconnect structure, comprising:
a substrate;
a dielectric layer disposed the substrate;
a first metal line disposed in the dielectric layer, having a first and second end, wherein the direction extending from the first end to the second end is parallel to a substrate surface;
a first plug and a second plug disposed on the first end of the first metal line, wherein the first plug is closer to the first end than the second plug;
a second metal line disposed on the dielectric layer, connecting the first metal line through the second plug.

19. (New)The interconnect structure as claimed in claim 18, wherein the second metal line does not connect to the first plug.